

**營業項目 / Business Items**

為 台灣：(名佳利、第一伸銅、旺昱) 主代理商。  
為 日本、美國、中國、韓國等高性能合金 指定代理商。  
Taiwan: (Minchali, First Copper, Wang Yu) Main sales representative.  
Appointed sales agency for high performance alloy in Japan, USA, China, Korea.

銅合金編號 Alloy No.	C1100	C1020	C1220	C5111	C5191	C5210	C2600	C2680	C2801
名稱 Type No.	紅銅系列 Copper Materials			磷銅系列 Phosphor Bronze Materials			黃銅系列 Brass Materials		
特性 Features	<ul style="list-style-type: none"> <li>導電性最佳 Best Electrical Conductivity</li> <li>熱傳導性最佳 Best Thermal Conductivity</li> <li>延展性最好 Best Extensibility</li> <li>加工成型最好 Best Molding Process</li> </ul>			<ul style="list-style-type: none"> <li>耐疲勞性佳 Good Resistance to Fatigue</li> <li>彈性強度佳 Good Flexible Strength</li> <li>抗腐蝕性佳 Good Resistance to Corrosion</li> </ul>			<ul style="list-style-type: none"> <li>導電位居中 Moderate Electrical Conductivity</li> <li>彈性位居中 Moderate Flexibility</li> <li>抗腐蝕性佳 Excellent Resistance to Corrosion</li> </ul>		
作用用途 Applications	<ul style="list-style-type: none"> <li>接線端子 Wiring Terminals</li> <li>散熱模組 Heat Radiation Modules</li> <li>高壓線圈 Hypertension Coils</li> <li>自動車端子 Automobile Terminals</li> <li>家電端子 Household Electrical terminals</li> <li>藝術品 Artifacts</li> </ul>			<ul style="list-style-type: none"> <li>電腦內外件端子 Computer Interior and Exterior terminals</li> <li>連接器端子 Connector Terminals</li> <li>半導體 Semiconductor</li> <li>通信設備 (手機, 網路等) Telecommunication Equipment (Cell Phones, Networks, etc.)</li> </ul>			<ul style="list-style-type: none"> <li>多媒體產品 Multimedia Products</li> <li>微型馬達內構部件 Miniature Motor Internal Parts</li> <li>網路設備 Network Equipment</li> <li>遊戲機設備 Game Machine Equipment</li> <li>藝術品 Artifacts</li> </ul>		



銅合金編號 Alloy No.	C7521	C7701	C7025	C7035	CuTi	C17200	C17510	EFTEC系列 Series			
									CuBe	CuBe820	C5240
名稱 Type No.	白銅 (洋白銅/鎳銅) White Copper (Western White Copper, Nickel Copper)		銅鎳矽 (高導電銅) Copper Nickel Silicone (High Electrical Conductivity Copper)		鈦銅 Ti-Cu	高鉍銅 High Beryllium -Copper	低鉍銅 Low beryllium -Copper	古河系列 高性能銅合金 Furukawa Series High Performance Copper Alloy			
特性 Features	<ul style="list-style-type: none"> <li>EMI高遮蔽 EMI High Obstruction</li> <li>高沾錫性 High Adhesiveness to Tin</li> </ul>		<ul style="list-style-type: none"> <li>高導電性 High Electric Conductivity</li> <li>高強度 High Strength</li> <li>高彈性 High Flexibility</li> </ul>		高強度 High Strength	可時效熱處理優化 Can be Time Effect Heat Treatment Prioritization	高導電與強度兼具 High Electrical Conductivity and High Strength	<ul style="list-style-type: none"> <li>高導電 High Electrical Conductivity</li> <li>高強度 High Strength</li> <li>高折彎曲度 High Bending Curvature</li> </ul>			
作用用途 Applications	<ul style="list-style-type: none"> <li>無線通訊 Radio Communication</li> <li>手機 Cell Phones</li> <li>醫療設備 Hospital Equipment</li> <li>信號設備 Signaling Equipment</li> </ul>		<ul style="list-style-type: none"> <li>手機端子 Cell Phone Terminals</li> <li>電池部品 Battery Parts</li> <li>電腦高電流傳輸匯流裝置 Computer High Current transmission Bus Bar Devices</li> <li>多媒體導航裝製 Multimedia Navigation Guiding Devices</li> </ul>		<ul style="list-style-type: none"> <li>微型端子 Miniature Terminals</li> <li>高壽命連接器 High Service Life Connectors</li> </ul>	<ul style="list-style-type: none"> <li>數位相機 Cell Phones</li> <li>電腦 Computers</li> <li>多媒體裝置 Digital Camera Multimedia Devices</li> </ul>	<ul style="list-style-type: none"> <li>電池端子 Battery Terminals</li> <li>電腦端子 Computer Terminals</li> <li>高電流產品 High Current Products</li> </ul>	<ul style="list-style-type: none"> <li>電腦內部機構件 Computer Interior Mechanisms</li> <li>手機微型機構件 Cell Phone Miniature Mechanisms</li> <li>數碼裝置 Multimedia Devices</li> <li>多媒體裝置 Coding Devices</li> <li>遊戲機 Game Players</li> <li>智慧型手機 Intelligent Cell Phones</li> </ul>			

**客製化需求  
Customer Requirements**

合金編號 Alloy Code	C194	Reflow 磷銅 Reflow Bronze	Reflow 黃銅 Reflow Brass
名稱 Type No.	導線框架材 Conductive Wire Frame Material	鍍錫磷銅 Tin Plated Bronze	鍍錫黃銅 Tin Plated Brass
特性 Features	高導電 High Electrical Conductivity	高鐸錫接點 High Welding Contact Points	高鐸錫接點 High Tin-welded Contact Point
作用用途 Applications	<ul style="list-style-type: none"> <li>IC 腳座 IC pins</li> <li>LED 框架 LED Framework</li> <li>微處理器內部框架 Microprocessor Internal Framework</li> </ul>	<ul style="list-style-type: none"> <li>板對板接點 Plate-to-plate Contact Point</li> <li>端子 Terminals</li> </ul>	<ul style="list-style-type: none"> <li>板對板接點 Plate-to-plate Contact Point</li> <li>端子 Terminal</li> </ul>

備註：可依客戶需求進行客製化